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October 2014

FDMS86102LZ

N-Channel Shielded Gate PowerTrench[®] MOSFET 100 V, 22 A, 25 m Ω

Features

- Shielded Gate MOSFET Technology
- Max $r_{DS(on)}$ = 25 m Ω at V_{GS} = 10 V, I_D = 7 A
- Max $r_{DS(on)}$ = 37 m Ω at V_{GS} = 4.5 V, I_D = 5.8 A
- HBM ESD protection level > 6 KV typical (Note 4)
- 100% UIL Tested
- RoHS Compliant



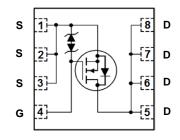
General Description

This N-Channel logic Level MOSFETs are produced using Fairchild Semiconductor's advanced PowerTrench® process that incorporates Shielded Gate technology. This process has been optimized for the on-state resistance and yet maintain superior switching performance. G-S zener has been added to enhance ESD voltage level.

Applications

- DC DC Conversion
- Inverter
- Synchronous Rectifier





MOSFET Maximum Ratings T_A = 25 °C unless otherwise noted

Symbol	Paramete	r		Ratings	Units
V_{DS}	Drain to Source Voltage			100	V
V_{GS}	Gate to Source Voltage			±20	V
I _D	Drain Current -Continuous	T _C = 25 °C		22	
	-Continuous	T _A = 25 °C	(Note 1a)	7	Α
	-Pulsed			40	
E _{AS}	Single Pulse Avalanche Energy		(Note 3)	84	mJ
D	Power Dissipation	T _C = 25 °C		69	W
P_{D}	Power Dissipation	T _A = 25 °C	(Note 1a)	2.5	VV
T_J , T_{STG}	Operating and Storage Junction Temperatur	e Range		-55 to +150	°C

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case	1.8	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1a)	50	C/VV

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDMS86102Z	FDMS86102LZ	Power 56	13 "	12 mm	3000 units

Electrical Characteristics T_J = 25 °C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Chara	cteristics					
BV_{DSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	100			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I_D = 250 μ A, referenced to 25 °C		70		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 80 V, V _{GS} = 0 V			1	μΑ
I _{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			±10	μΑ

On Characteristics

V _{GS(th)}	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu A$	1.0	1.5	2.5	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I_D = 250 μ A, referenced to 25 °C		-6		mV/°C
		V _{GS} = 10 V, I _D = 7 A		18.6	25	
r _{DS(on)}	Static Drain to Source On Resistance	$V_{GS} = 4.5 \text{ V}, I_D = 5.8 \text{ A}$		23.5	37	mΩ
		$V_{GS} = 10 \text{ V}, I_D = 7 \text{ A}, T_J = 125 ^{\circ}\text{C}$		31.2	42	1
9 _{FS}	Forward Transconductance	V _{DS} = 5 V, I _D = 7 A		26		S

Dynamic Characteristics

C _{iss}	Input Capacitance	V 50 V V 0 V	979	1305	pF
C _{oss}	Output Capacitance	$V_{DS} = 50 \text{ V}, V_{GS} = 0 \text{ V},$ $f = 1 \text{ MHz}$	175	235	pF
C _{rss}	Reverse Transfer Capacitance	1 = 1 101112	8.9	15	pF
R_g	Gate Resistance		0.9		Ω

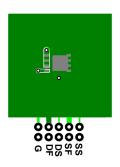
Switching Characteristics

t _{d(on)}	Turn-On Delay Time		6.7	14	ns
t _r	Rise Time	V _{DD} = 50 V, I _D = 7 A,	2.6	10	ns
t _{d(off)}	Turn-Off Delay Time	$V_{GS} = 10 \text{ V}, R_{GEN} = 6 \Omega$	19	35	ns
t _f	Fall Time		2.5	10	ns
$Q_{g(TOT)}$	Total Gate Charge	V _{GS} = 0 V to 10 V	16	22	nC
$Q_{g(TOT)}$	Total Gate Charge	$V_{GS} = 0 \text{ V to } 4.5 \text{ V}$ $V_{DD} = 50 \text{ V},$ $I_{D} = 7 \text{ A}$	7.8	11	nC
Q_{gs}	Total Gate Charge	1 _D = 7 A	2.4		nC
Q_{gd}	Gate to Drain "Miller" Charge		2.6		nC

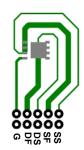
Drain-Source Diode Characteristics

V _{SD}	Source to Drain Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 7 \text{ A}$	(Note 2)	0.81	1.3	\/
		$V_{GS} = 0 \text{ V}, I_{S} = 2 \text{ A}$	(Note 2)	0.72	1.2	V
t _{rr}	Reverse Recovery Time	-I _F = 7 A, di/dt = 100 A/μs		35	57	ns
Q _{rr}	Reverse Recovery Charge			25	40	nC

^{1.} $R_{\theta JA}$ is determined with the device mounted on a 1 in² pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.



a. 50 °C/W when mounted on a 1 in² pad of 2 oz copper



b. 125 °C/W when mounted on a minimum pad of 2 oz copper

- 2. Pulse Test: Pulse Width < 300 $\mu\text{s},$ Duty cycle < 2.0%.
- 3. Starting T $_{J}$ = 25 °C; N-ch: L = 1 mH, I $_{AS}$ = 13 A, V $_{DD}$ = 90 V, V $_{GS}$ = 10 V.
- 4. The diode connected between gate and source serves only as protection against ESD. No gate overvoltage rating is implied.

Typical Characteristics T_J = 25 °C unless otherwise noted

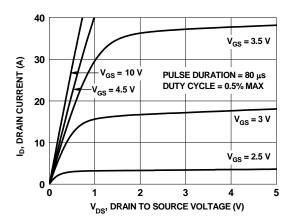


Figure 1. On-Region Characteristics

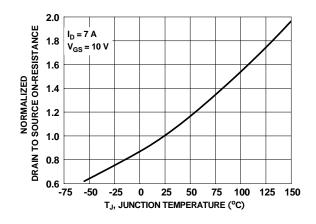


Figure 3. Normalized On-Resistance vs Junction Temperature

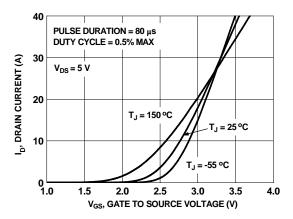


Figure 5. Transfer Characteristics

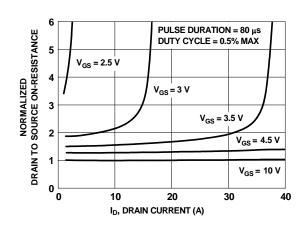


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

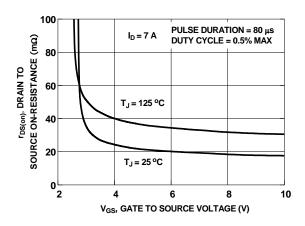


Figure 4. On-Resistance vs Gate to Source Voltage

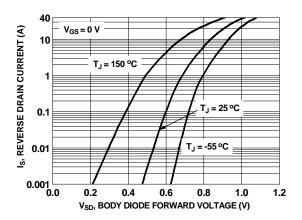


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics $T_J = 25$ °C unless otherwise noted

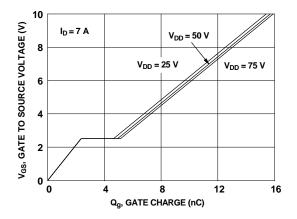


Figure 7. Gate Charge Characteristics

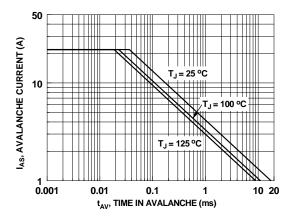


Figure 9. Unclamped Inductive Switching Capability

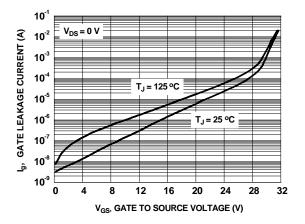


Figure 11. Gate Leakage Current vs Gate to Source Voltage

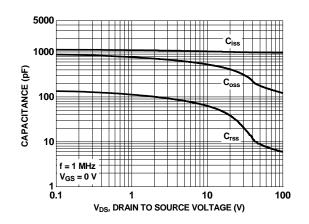


Figure 8. Capacitance vs Drain to Source Voltage

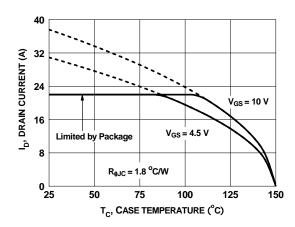


Figure 10. Maximum Continuous Drain Current vs Case Temperature

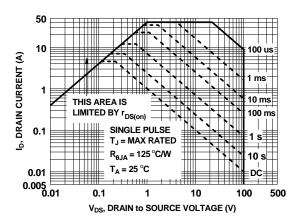


Figure 12. Forward Bias Safe Operating Area



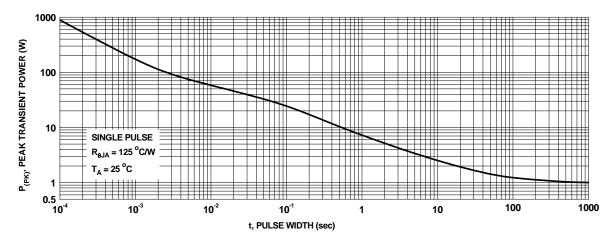


Figure 13. Single Pulse Maximum Power Dissipation

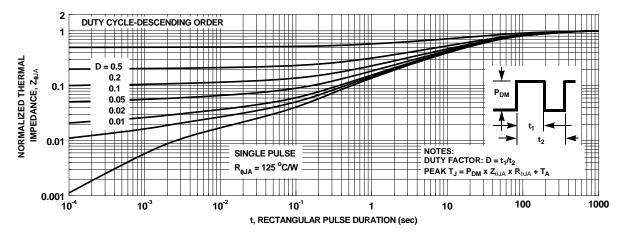
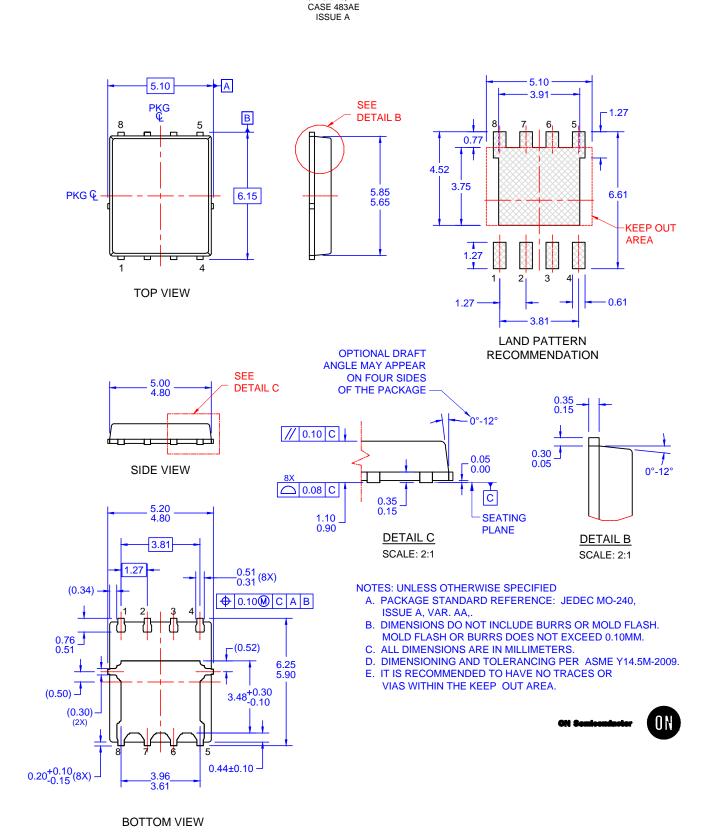


Figure 14. Junction-to-Ambient Transient Thermal Response Curve



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